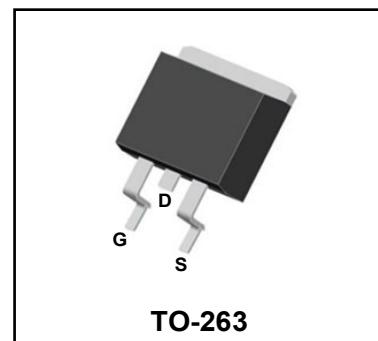


WMM053N10HGS

100V N-Channel Enhancement Mode Power MOSFET

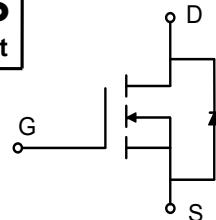
Description

WMM053N10HGS uses Wayon's advanced power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.



Features

- $V_{DS} = 100V$, $I_D = 120A$
- $R_{DS(on)} < 5.5m\Omega$ @ $V_{GS} = 10V$
- Green Device Available
- Low Gate Charge
- 100% EAS Guaranteed



Applications

- Power Management Switches
- DC/DC Converter
- LED Backlighting

Absolute Maximum Ratings ($T_A = 25^\circ C$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current <small>$T_C=25^\circ C$</small>	I_D	120	A
		76	
Pulsed Drain Current ¹	I_{DM}	480	A
Single Pulse Avalanche Energy ²	EAS	245	mJ
Total Power Dissipation	P_D	164.5	W
Operating Junction and Storage Temperature Range	T_J , T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	56	°C/W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	0.76	°C/W

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	I_{DSS}	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	μA
$T_J=100^\circ\text{C}$			-	-	100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2	3	4	V
Drain-Source on-Resistance ⁴	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	-	4.5	5.5	$\text{m}\Omega$
Forward Transconductance ⁴	g_{fs}	$V_{\text{DS}} = 10\text{V}, I_D = 20\text{A}$	-	59	-	S
Dynamic Characteristics⁵						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	4903	-	pF
Output Capacitance	C_{oss}		-	662	-	
Reverse Transfer Capacitance	C_{rss}		-	25	-	
Gate Resistance	R_g	$f = 1\text{MHz}$	-	1.5	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q_g	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 50\text{V}, I_D = 20\text{A}$	-	82.5	-	nC
Gate-Source Charge	Q_{gs}		-	24	-	
Gate-Drain Charge	Q_{gd}		-	23.5	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 50\text{V}, R_G = 3\Omega, I_D = 20\text{A}$	-	15.8	-	ns
Rise Time	t_r		-	12.8	-	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		-	34	-	
Fall Time	t_f		-	6.8	-	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 20\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	56	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	102	-	nC
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$I_S = 20\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	1.2	V
Continuous Source Current	$T_c = 25^\circ\text{C}$	I_S	-	-	120	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})} = 150^\circ\text{C}$.
2. The EAS data shows Max. rating . The test condition is $V_{\text{DD}} = 25\text{V}, V_{\text{GS}} = 10\text{V}, L = 0.4\text{mH}, I_{\text{AS}} = 35\text{A}$.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

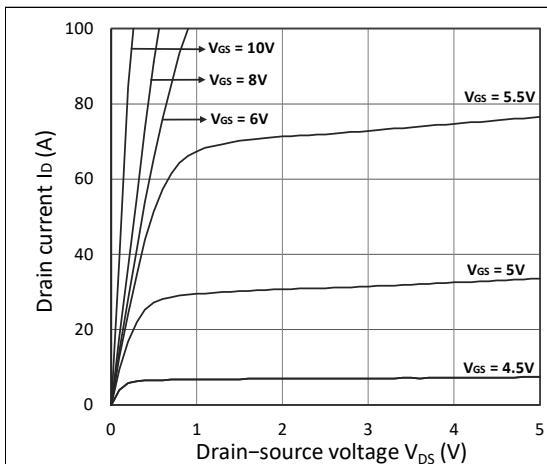


Figure 1. Output Characteristics

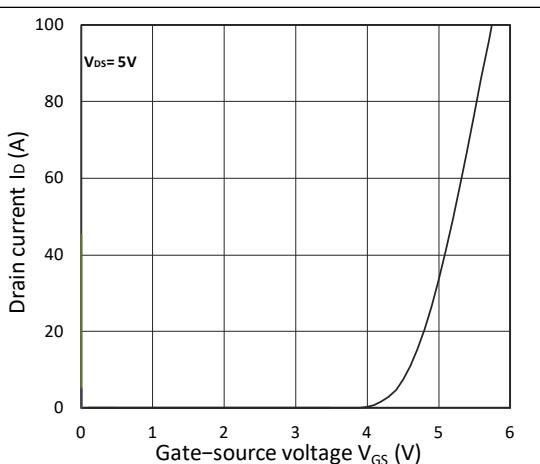


Figure 2. Transfer Characteristics

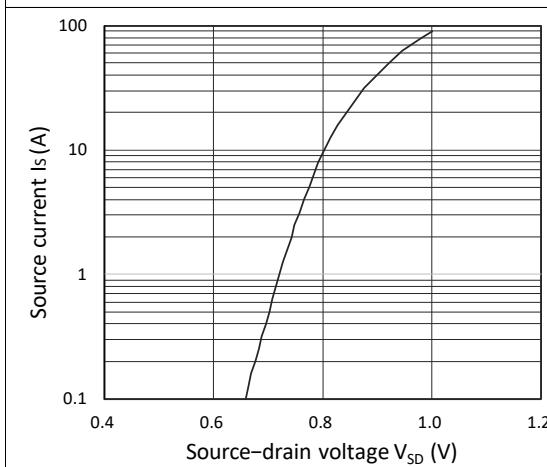
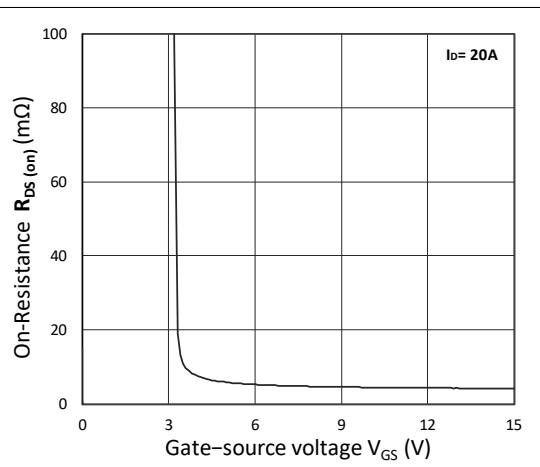
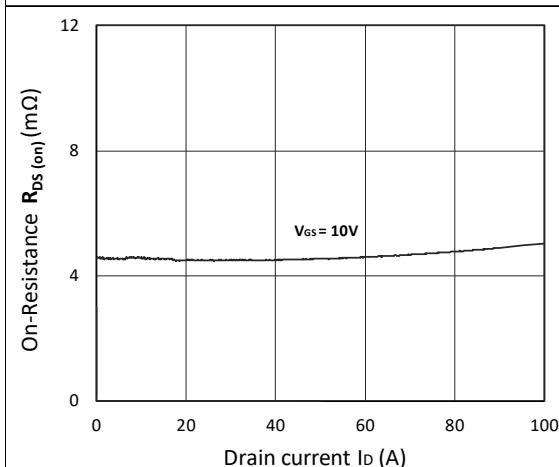
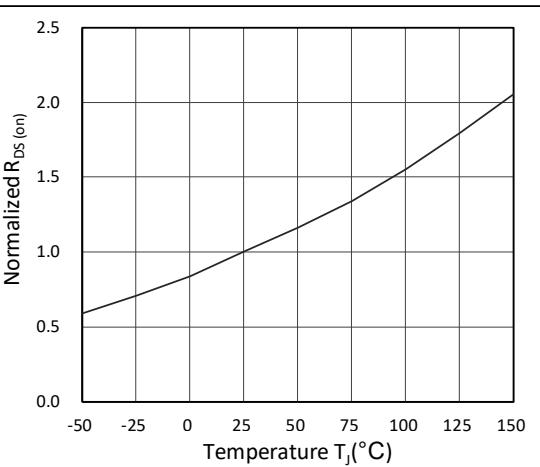
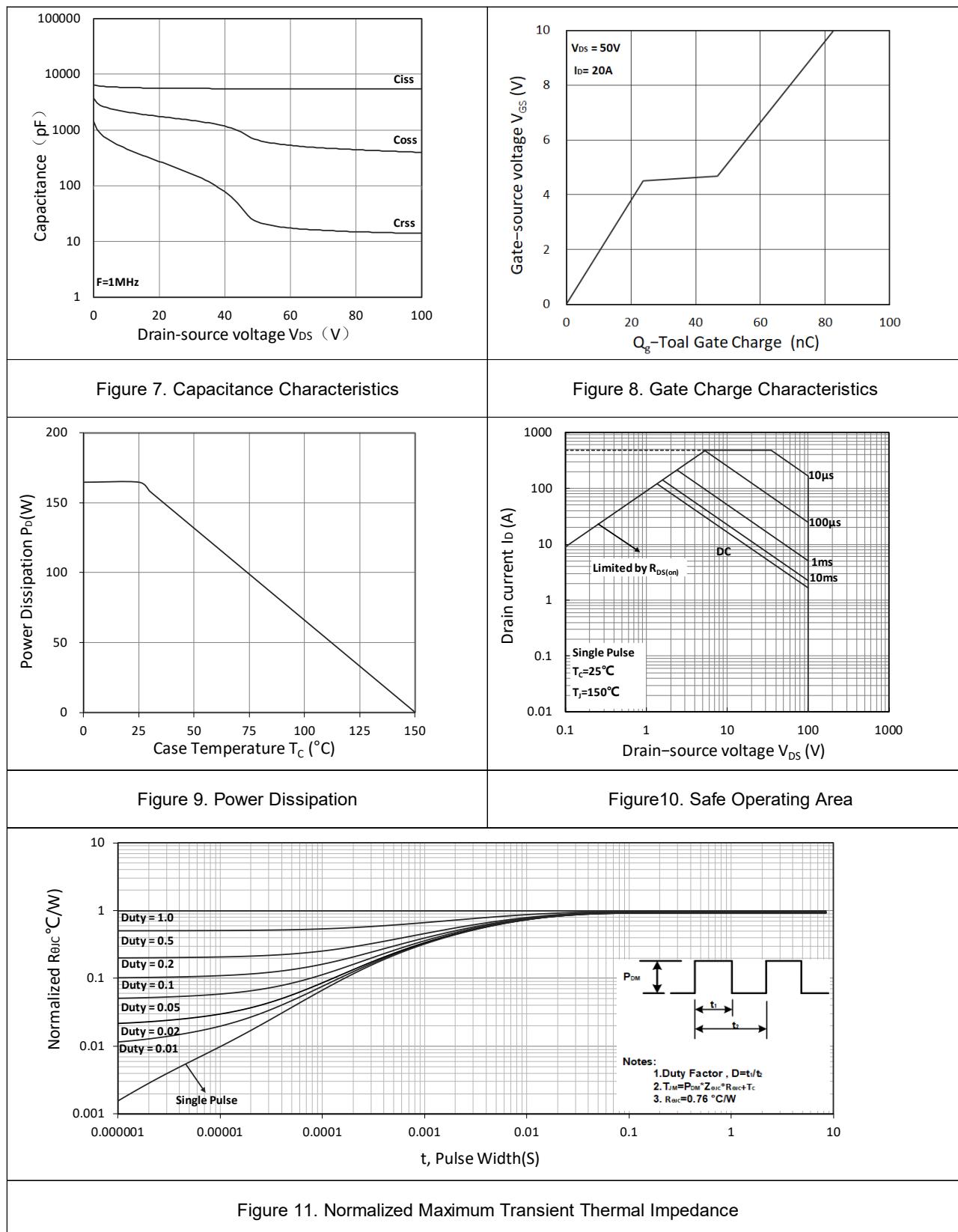
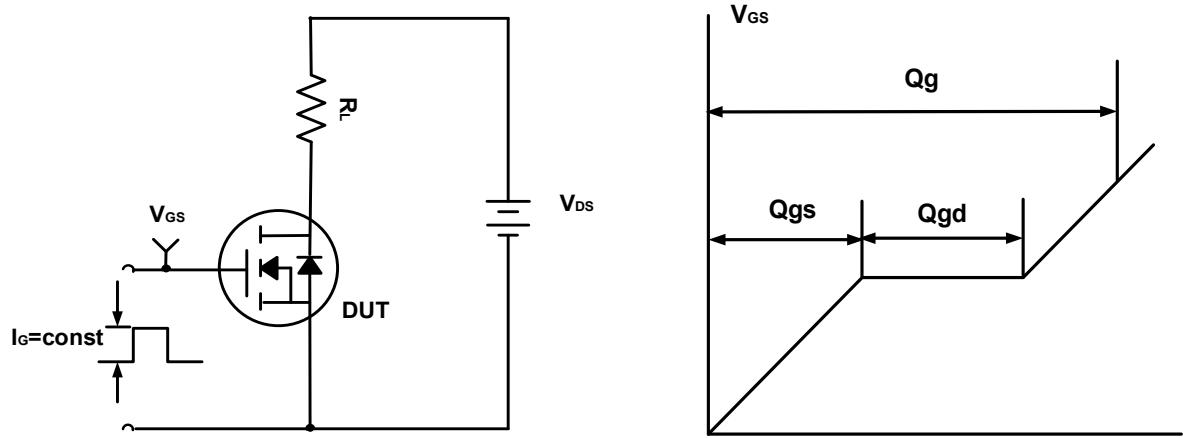
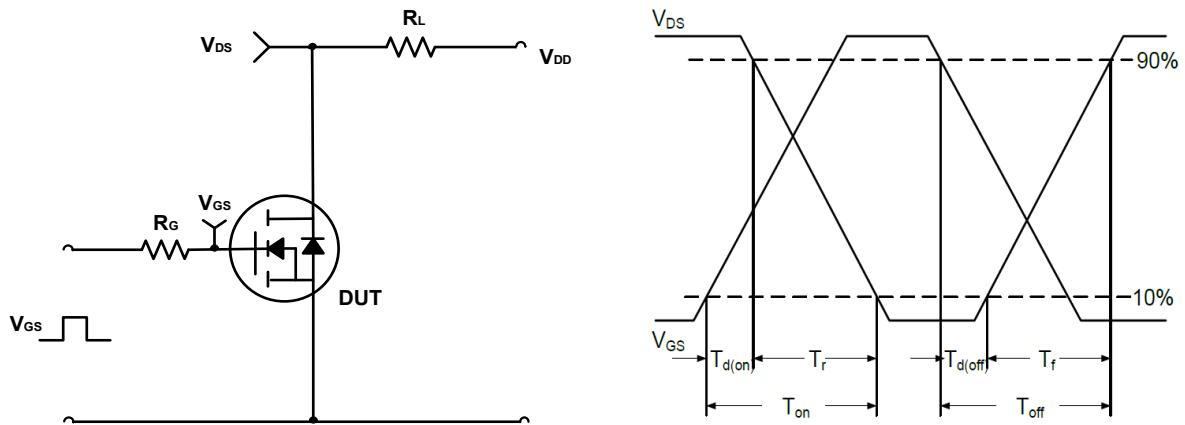
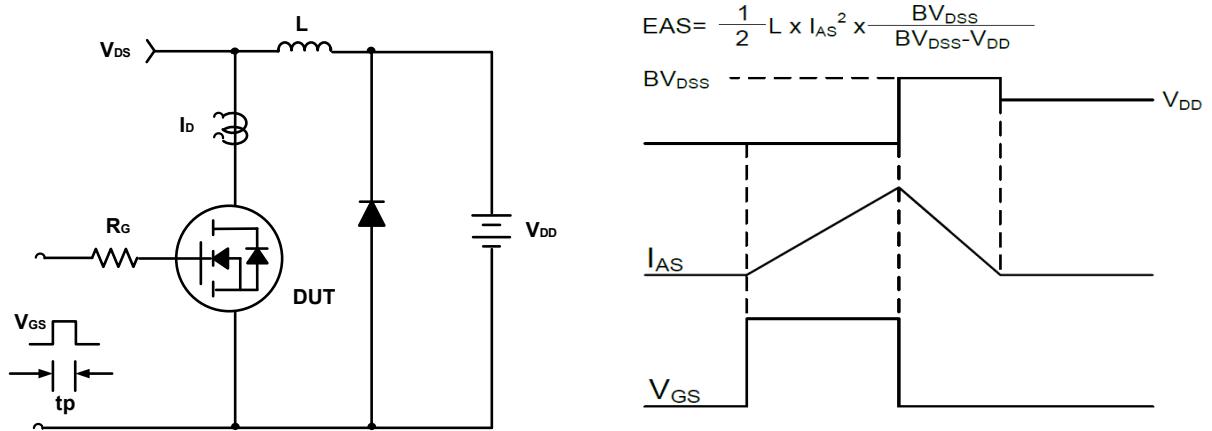


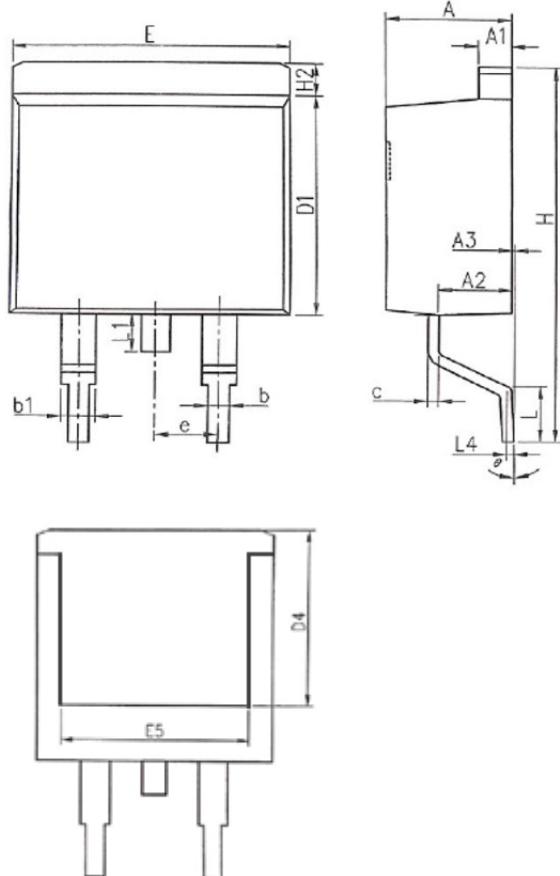
Figure 3. Forward Characteristics of Reverse

Figure 4. $R_{DS(on)}$ vs. V_{GS} Figure 5. $R_{DS(on)}$ vs. I_D Figure 6. Normalized $R_{DS(on)}$ vs. Temperature



Test Circuit**Figure A. Gate Charge Test Circuit & Waveforms****Figure B. Switching Test Circuit & Waveforms****Figure C. Unclamped Inductive Switching Circuit & Waveforms**

Mechanical Dimensions for TO-263



COMMON DIMENSIONS

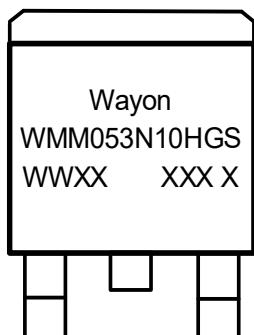
SYMBOL	MM	
	MIN	MAX
A	4.37	4.89
A1	1.17	1.42
A2	2.20	2.90
A3	0.00	0.25
b	0.70	0.96
b1	1.17	1.47
c	0.28	0.60
D1	8.45	9.30
D4	6.60	-
E	9.80	10.40
E5	7.06	-
e	2.54BSC	
H	14.70	15.70
H2	1.07	1.47
L	2.00	2.80
L1	-	1.75
L4	0.254BSC	
θ	0°	9°

WMM053N10HGS

Ordering Information

Part	Package	Marking	Packing method
WMM053N10HGS	TO-263	WMM053N10HGS	Tape and Reel

Marking Information



WMM053N10HGS = Device code

WWXX XXX X= Date code